

Normally – OFF Silicon Carbide Super Junction Transistor

V _{DS}	=	650 V
$V_{DS(ON)}$	=	1.7 V
I _D	=	16 A
R _{DS(ON)}	=	105 mΩ

Features

- 250 °C maximum operating temperature
- Temperature independent switching performance
- Gate oxide free SiC switch
- Suitable for connecting an anti-parallel diode
- · Positive temperature coefficient for easy paralleling
- Low gate charge
- Low intrinsic capacitance

Package

RoHS Compliant





SMD0.5 / TO - 276 (Hermetic Package)

Advantages

- Low switching losses
- Higher efficiency
- · High temperature operation
- · High short circuit withstand capability

Applications

- Down Hole Oil Drilling, Geothermal Instrumentation
- Hybrid Electric Vehicles (HEV)
- Solar Inverters
- Switched-Mode Power Supply (SMPS)
- Power Factor Correction (PFC)
- Induction Heating
- Uninterruptible Power Supply (UPS)
- Motor Drives

Maximum Ratings at T_i = 250 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Drain – Source Voltage	V_{DS}	V _{GS} = 0 V	650	V
Continuous Drain Current	I _D	T _C = 155 °C	16	Α
Gate Peak Current	I_{GM}		5	Α
Reverse Gate – Source Voltage	V_{GS}		200	V
Reverse Drain – Source Voltage	V_{DS}		40	V
Power Dissipation	P _{tot}	T _C = 25 °C	27	W
Operating and Storage Temperature	T_{j},T_{stg}		-55 to 250	°C

Electrical Characteristics at T_i = 250 °C, unless otherwise specified

Parameter	Cumhal	Conditions	Values		1114	
	Symbol	Conditions -	min.	typ.	max.	Unit
On Characteristics						
		I_D = 16 A, I_G = 500 mA, T_j = 25 °C		1.7		
Drain – Source On Voltage	$V_{DS(ON)}$	I_D = 16 A, I_G = 1000 mA, T_j = 175 °C		2.7		V
		I_D = 16 A, I_G = 1000 mA, T_j = 250 °C		4.3		
		I_D = 16 A, I_G = 500 mA, T_j = 25 °C		105		
Drain – Source On Resistance	$R_{DS(ON)}$	I_D = 16 A, I_G = 1000 mA, T_j = 175 °C		180		mΩ
	, ,	I_D = 16 A, I_G = 1000 mA, T_j = 250 °C		290		
Gate Forward Voltage	V	I_G = 500 mA, T_j = 25 °C		3		V
	$V_{GS(FWD)}$	$I_G = 500 \text{ mA}, T_j = 250 \text{ °C}$		2.6		V
DC Current Gain	ρ	V _{DS} = 5 V, I _D = 20 A, T _j = 25 °C		115		
	β	$V_{DS} = 5 \text{ V}, I_{D} = 20 \text{ A}, T_{i} = 250 ^{\circ}\text{C}$		75		

Off Characteristics

		$V_R = 650 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 25 \text{ °C}$	1	
Drain Leakage Current	I _{DSS}	V_R = 650 V, V_{GS} = 0 V, T_j = 175 °C	7	μΑ
		$V_{P} = 650 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_{i} = 250 \text{ °C}$	45	



Electrical Characteristics at T_j = 250 °C, unless otherwise specified

Parameter	Cymahal	Conditions	Values		1114	
	Symbol	Conditions	min.	typ.	max.	Unit
Dynamic Characteristics						
Input Capacitance	C_{iss}	V - 25 V V - 0 V		1534		pF
Output Capacitance	C_{oss}	V_{DS} = 35 V, V_{GS} = 0 V, f = 1 MHz, T_{vi} = 25 °C		157		pF
Reverse Transfer Capacitance	C_{rss}	1 - 1 Wil 12, Tvj - 25 C		157		pF
Switching Characteristics						
Turn On Delay Time	$t_{d(on)}$			5		ns
Rise Time	t _r	$V_{DD} = 400 \text{ V}, I_D = 20 \text{ A},$		37		ns
Turn Off Delay Time	$t_{\sf d(off)}$	$R_{G(on)} = R_{G(off)} = 22 \Omega$		68		ns
Fall Time	t _f	$V_{GS} = -8/15 \text{ V}, T_i = 175 \text{ °C}$		78		ns
Turn-On Energy Per Pulse	E _{on}	Refer to Figure 10 for gate drive current waveforms		66		μJ
Turn-Off Energy Per Pulse	E _{off}			365		μJ
Total Switching Energy	E _{ts}			431		μJ
Turn On Delay Time	t _{d(on)}			7		ns
Rise Time	t _r	V _{DD} = 400 V, I _D = 20 A,		38		ns
Turn Off Delay Time	$t_{d(off)}$	$R_{G(on)} = R_{G(off)} = 22 \Omega,$		85		ns
Fall Time	t _f	V _{GS} = -8/15 V ,T _j = 250 °C Refer to Figure 10 for gate drive current waveforms		86		ns
Turn-On Energy Per Pulse	E _{on}			64		μJ
Turn-Off Energy Per Pulse	E _{off}			395		μJ
Total Switching Energy	E _{ts}]		459		μJ
Thermal Characteristics						
Thermal resistance, junction - case	R _{thJC}			0.6		°C/W

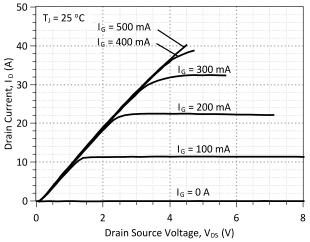


Figure 1: Typical Output Characteristics at 25 °C

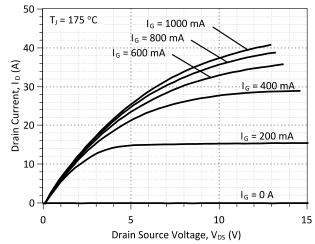


Figure 2: Typical Output Characteristics at 175 °C



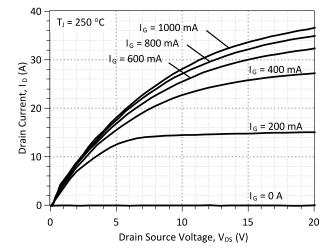


Figure 3: Typical Output Characteristics at 250 °C

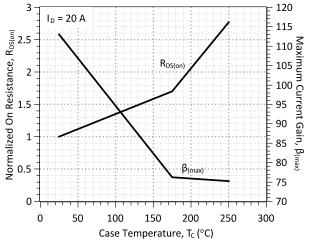


Figure 5: Normalized On-Resistance and Current Gain vs. Temperature

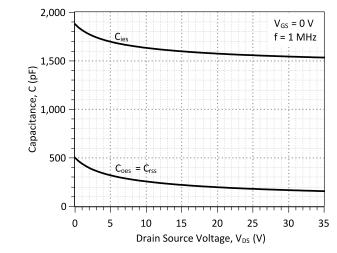


Figure 7: Typical Capacitance vs Drain-Source Voltage

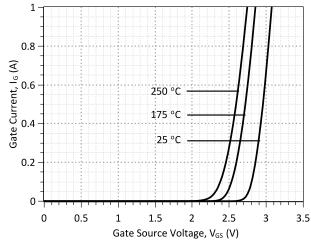


Figure 4: Typical Gate Source I-V Characteristics vs.
Temperature

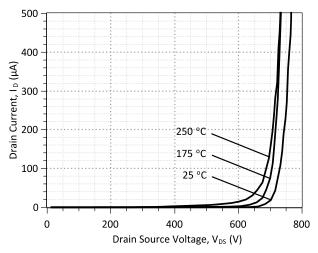


Figure 6: Typical Blocking Characteristics

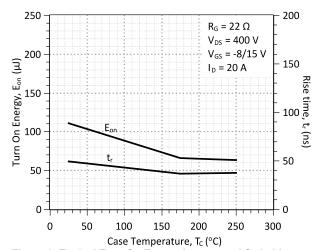


Figure 8: Typical Turn On Energy Losses and Switching Times vs. Temperature



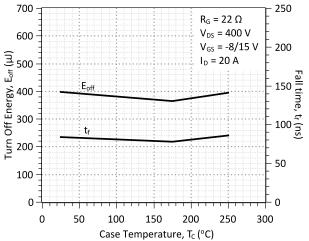


Figure 9: Typical Turn Off Energy Losses and Switching Times vs. Temperature

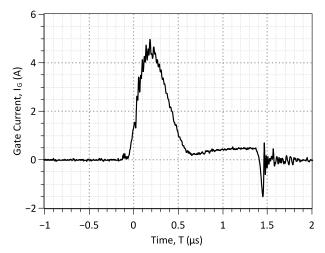
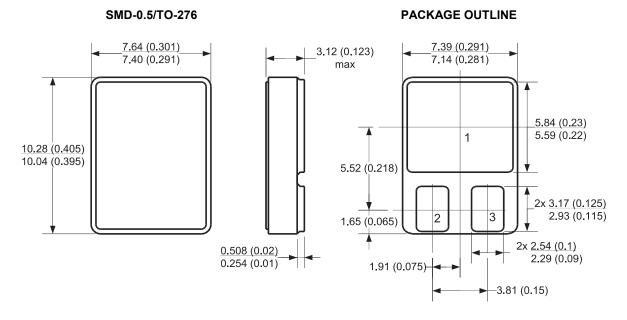


Figure 10: Typical Gate-Source Switching Waveforms

Package Dimensions:



- 1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
 2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS



Revision History					
Date	Revision	Comments	Supersedes		
2012/08/24	0	Initial release			

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